

Docket No.: GR 01 P 0922

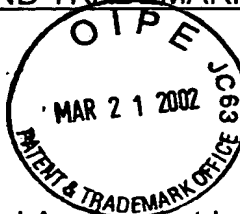
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By: 

Date: March 14, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Kurt Gross et al.
Applic. No. : 10/057,154
Filed : January 25, 2002
Title : Carrier with a Metal Area and at Least One Chip Configured on the Metal Area



INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

United States Patent No. 4,872,047 (Fister et al.), dated October 3, 1989;

United States Patent No. 5,654,586 (Schwarzbauer), dated August 5, 1997;

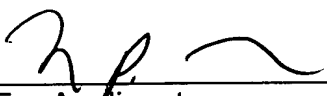
German Published, Non-Prosecuted Patent Application DE 34 14 065 A1 (Fellinger et al.), dated December 12, 1985, configuration of at least one electronic component mounted on a substrate and method for producing such a configuration;

European Patent Application EP 0 139 205 A2 (Lauterbach), dated May 2, 1985, method for producing semiconductor components with a metal substrate;

French Patent Application FR 2 305 025 (Gremillet), dated October 15, 1976,
component connecting a semiconductor device with its support and a device consisting
of such an element.

If no translation of pertinent portions of any foreign language patents or publications
mentioned above is included with the aforementioned copies of those applications,
patents and/or publications, it is because no existing translation is readily available to
the applicant.

Respectfully submitted,



For Applicants

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Date: March 14, 2002

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